

IN THE UNITED STATES PATENT AND TRADE MARK OFFICE

In re the Application of

Konecni et al.

Serial No.: 08/988,686

Filed: 12/11/97

For: **METHOD AND SYSTEM FOR SELECTIVELY COUPLING A CONDUCTIVE MATERIAL TO A SURFACE OF A SEMICONDUCTOR DEVICE**

Docket No.: TI-22166

Art Unit: 2823

Examiner: Eaton, K.



Handwritten notes: A.F. #2823 \$, #12, App, B2ref, Tushy, G-d+u

Assistant Commissioner
for Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner of Patents, Washington, D.C. 20231 on **March 20, 2000**
Jeff Quan

Dear Sir:

Applicant hereby appeals to the Board of Patent Appeals from the decision of the Primary Examiner dated **11/23/99** all rejected claims.

The item(s) checked below are appropriate:

1. ☒ An extension of time to respond to the final rejection

_____ was granted on _____

☒ is requested for 1 month(s).

2. ☐ A timely-response to the final rejection has been filed, as provided in 841 O.G. 1411.

3. ☒ Fee \$300.00:

_____ Not required (*Fee paid in prior appeal*)

☒ The Commissioner is hereby authorized to charge any fees which may be required, or credit any overpayment to Deposit Account No. 20-0668. An original and two copies of this sheet are enclosed.

RECEIVED

APR 06 2000

TECHNOLOGY CENTER 2800

Signature [Rule 191(b)]

04/05/2000 ABRAHIM 00000064 200668 08988686

02 FC:120 300.00 CH

Texas Instruments Incorporated
PO Box 655474, MS 3999
Dallas, TX 75265
(972) 917-4418

Handwritten signature of Mark A. Valetti

Mark A. Valetti
Attorney for Applicant(s)
Reg. No. 36,707